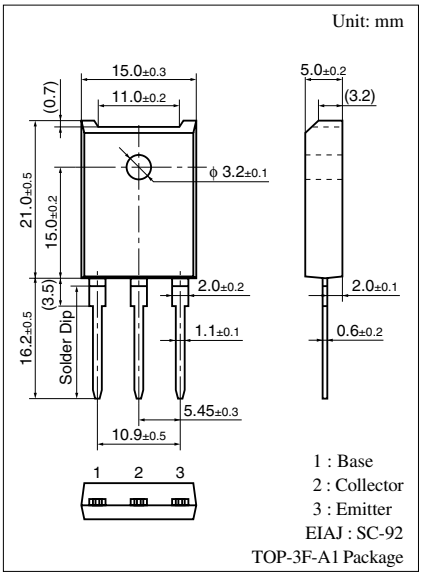
2SC3507

Silicon NPN triple diffusion planar type

For high breakdown voltage high-speed switching



■ Features

- High-speed switching
- High collector to base voltage V_{CBO}
- Satisfactory linearity of forward current transfer ratio h_{FE}
- Full-pack package which can be installed to the heat sink with one screw

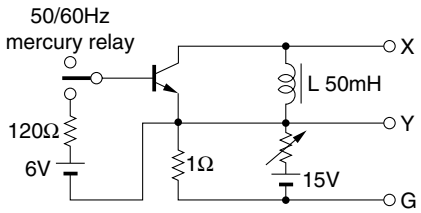
■ Absolute Maximum Ratings $T_C = 25°C$

Parameter		Symbol	Rating	Unit
Collector to base voltage		V_{CBO}	1 000	V
Collector to emitter voltage		V_{CES}	1 000	V
		V_{CEO}	800	V
Emitter to base voltage		V_{EBO}	7	V
Peak collector current		I_{CP}	10	A
Collector current		I_C	5	A
Base current		I_B	3	A
Collector power dissipation	$T_C = 25°C$	P_C	80	W
	$T_a = 25°C$		3	
Junction temperature		T_j	150	°C
Storage temperature		T_{stg}	−55 to +150	°C

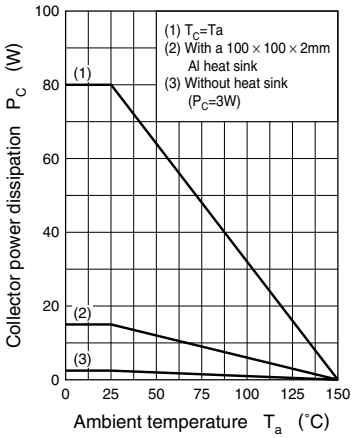
■ Electrical Characteristics $T_C = 25°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector cutoff current	I_{CBO}	V_{CB} = 1 000 V, I_E = 0			50	µA
Emitter cutoff current	I_{EBO}	V_{EB} = 7 V, I_C = 0			50	µA
Collector to emitter voltage *	$V_{CEO(sus)}$	I_C = 0.5 A, L = 50 mH	800			V
Forward current transfer ratio	h_{FE}	V_{CE} = 5 V, I_C = 3 A	6			
Collector to emitter saturation voltage	$V_{CE(sat)}$	I_C = 3 A, I_B = 0.6 A			1.5	V
Base to emitter saturation voltage	$V_{BE(sat)}$	I_C = 3 A, I_B = 0.6 A			1.5	V
Transition frequency	f_T	V_{CE} = 5 V, I_C = 0.5 A, f = 1 MHz		6		MHz
Turn-on time	t_{on}	I_C = 3 A, I_{B1} = 0.6 A, I_{B2} = −1.2 A,			1	µs
Storage time	t_{stg}	V_{CC} = 250 V			2.5	µs
Fall time	t_f				0.5	µs

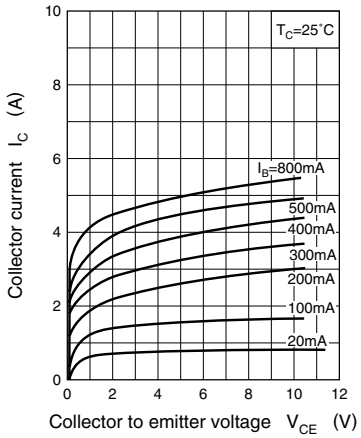
Note) *: $V_{CEO(sus)}$ Test circuit



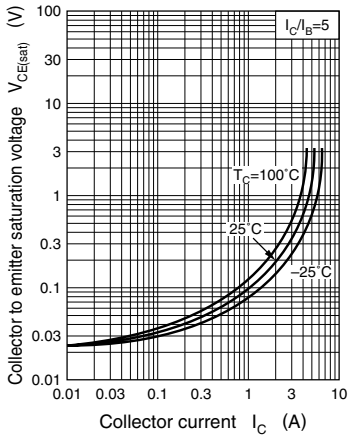
P_C — T_a



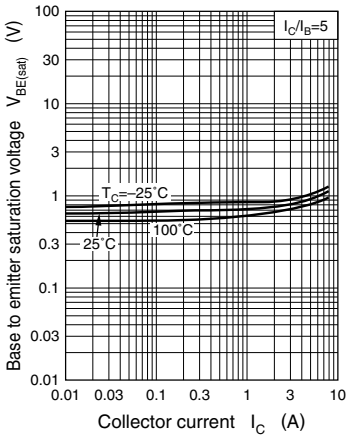
I_C — V_{CE}



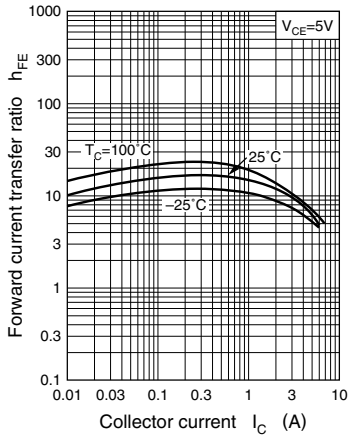
$V_{CE(sat)}$ — I_C



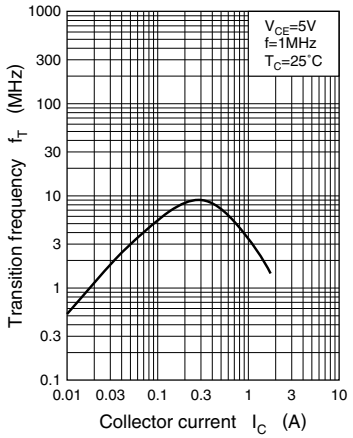
$V_{BE(sat)}$ — I_C



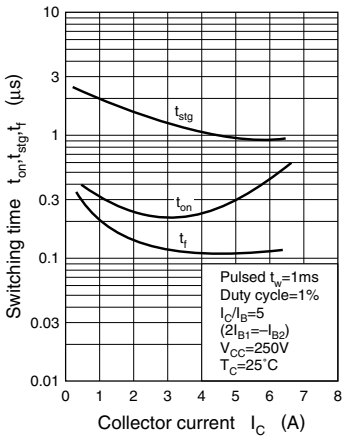
h_{FE} — I_C



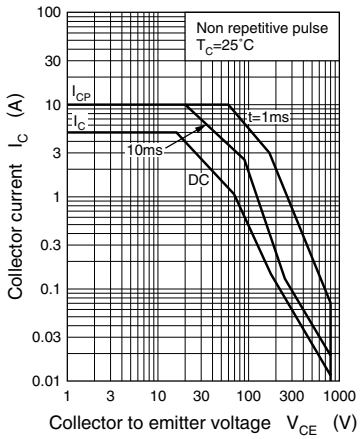
f_T — I_C



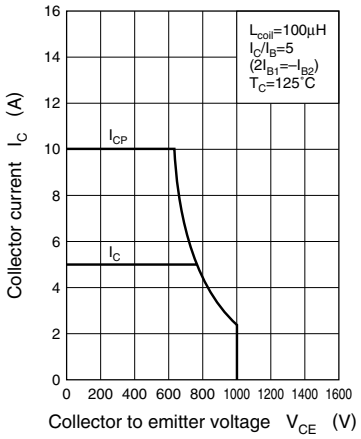
t_{on}, t_{stg}, t_f — I_C



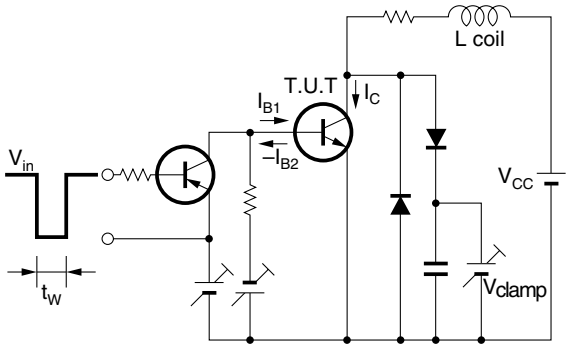
Area of safe operation (ASO)



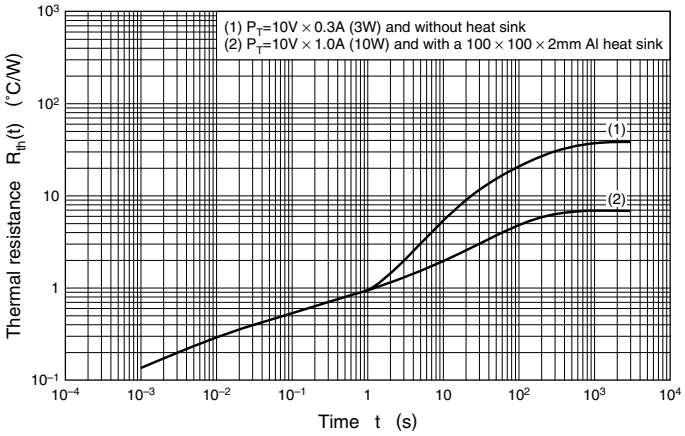
Area of safe operation, reverse bias ASO



Reverse bias ASO measuring circuit



$R_{th(t)}$ — t



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